

• General Description

Through advanced trench and field cutoff technology to provide very low $V_{CE(sat)}$, low gate charge, and excellent switching performance.

• Features

- Very low $V_{CE(sat)}$
- Low switching power loss
- Low switching surge and noise
- Low thermal resistance
- High short circuit capability (10us)

• Application

- Energy Generation
- Industrial power supplies
- Welding

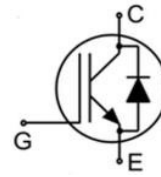
• Ordering Information:

| | |
|---------------------------|-----------------|
| Part NO. | ZMBG15N120SD1AC |
| Marking | BG15N120SD1A |
| Packing information | TUBE BULK |
| Basic ordering unit (pcs) | 600 |

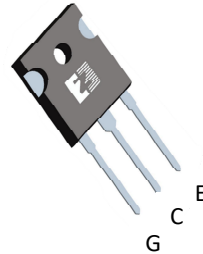
• Absolute Maximum Ratings ($T_C=25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Value | Unit |
|--------------------------------|---------------|---|-------------|------------------|
| Collector-emitter voltage | V_{CE} | | 1200 | V |
| Gate-emitter voltage | V_{GE} | | ± 30 | V |
| Collector current | I_C | $T_C=25^\circ\text{C}$ | 30 | A |
| | I_C | $T_C=100^\circ\text{C}$ | 15 | A |
| Pulsed collector current | I_{CM} | $T_C=25^\circ\text{C}$ | 45 | A |
| Diode forward current | I_F | $T_C=25^\circ\text{C}$ | 30 | A |
| | I_F | $T_C=100^\circ\text{C}$ | 15 | A |
| | $I_{F,pulse}$ | $T_C=25^\circ\text{C}$ | 45 | A |
| Total power Dissipation | P_D | $T_C=25^\circ\text{C}$ | 203 | W |
| Total Power Dissipation | P_D | $T_A=25^\circ\text{C}$ | 3.8 | W |
| Short Circuit Withstand Time | T_{sc} | $V_{GE}=15\text{ V}, V_{CE}=600\text{ V}, T_J=25^\circ\text{C}$ | 10 | us |
| Operating Junction Temperature | T_J | | -55 to +175 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | | -55 to +175 | $^\circ\text{C}$ |

• Product Summary



$V_{CE} = 1200\text{V}$
 $V_{CE(sat)} = 1.85\text{V}$
 $I_C = 15\text{A}$



TO-247



•Thermal resistance

| Parameter | Symbol | Min. | Typ. | Max. | Unit |
|---|--------------------|------|------|------|------|
| Thermal resistance, junction - case IGBT | R_{thJC} | - | - | 0.74 | °C/W |
| Thermal resistance, junction - case diode | R_{thJC} | - | - | 2.4 | °C/W |
| Thermal resistance, junction-ambient | R_{thJA}° | - | - | 40 | °C/W |
| Soldering temperature (total time<10s) | Tsold | - | - | 260 | °C |

•Electronic Characteristics

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------------------|---------------|---|------|------|------|---------|
| Collector-emitter breakdown voltage | $V_{(BR)CES}$ | $V_{GE}=0V, I_C=250\mu A$ | 1200 | - | - | V |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $V_{GE}=15V, I_C=15A$ | - | 1.85 | 2.30 | V |
| | | $V_{GE}=15V, I_C=15A, T_J=175^{\circ}C$ | - | 2.3 | - | |
| Gate-emitter threshold voltage | $V_{GE(th)}$ | $V_{CE}=V_{GE}, I_C=1.5mA$ | 5.0 | 6.0 | 7.0 | V |
| Forward on-voltage | V_F | $I_F=15A, T_J=25^{\circ}C$ | - | 1.9 | 2.3 | V |
| | | $I_F=15A, T_J=125^{\circ}C$ | - | 1.6 | 2.2 | |
| | | $I_F=15A, T_J=175^{\circ}C$ | - | 1.45 | 2.0 | |
| Zero gate voltage collector current | I_{CES} | $V_{GE}=0V, V_{CE}=1200V, T_J=25^{\circ}C$ | - | - | 10.0 | μA |
| Zero gate voltage collector current | I_{CES} | $V_{GE}=0V, V_{CE}=1200V, T_J=175^{\circ}C$ | - | - | 10.0 | mA |
| Gate-emitter leakage current | I_{GES} | $V_{GE}=\pm 30V, V_{CE}=0V$ | - | - | 100 | nA |

•Dynamic characteristics , at $T_J=25^{\circ}C$

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|------------------------------|-----------|--------------------------------------|------|------|------|------|
| Input capacitance | C_{ies} | $f=1MHz, V_{CE}=600V$ | - | 1325 | - | pF |
| Output capacitance | C_{oes} | | - | 21 | - | |
| Reverse transfer capacitance | C_{res} | | - | 4 | - | |
| Total gate charge | Q_g | $V_{CC}=600V, I_C=15.0A, V_{GE}=15V$ | - | 68 | - | nC |
| Gate-emitter charge | Q_{ge} | | - | 12 | - | nC |
| Gate-collector charge | Q_{gc} | | - | 40 | - | nC |

SwitchingCharacteristic, at $T_J=25^{\circ}C$

| | | | | | | |
|------------------------|--------------|---|---|-------|---|----|
| Turn-on delay time | $t_{D(on)}$ | $T_J=25^{\circ}C, V_{CC}=600V, I_C=15A, V_{GE}=-8/15V, R_g=6.2\Omega, L=200\mu H$ | - | 27.9 | - | ns |
| Turn-on rise time | t_r | | - | 58.5 | - | ns |
| Turn-off delay time | $t_{D(off)}$ | | - | 76.2 | - | ns |
| Turn-off fall time | t_f | | - | 29.4 | - | ns |
| Turn-on energy | E_{on} | | - | 0.772 | - | mJ |
| Turn-off energy | E_{off} | | - | 0.499 | - | mJ |
| Total switching energy | E_{ts} | | - | 1.271 | - | mJ |

Switching Characteristic, at $T_J=150^\circ\text{C}$

| | | | | | | |
|------------------------|--------------|---|---|-------|---|----|
| Turn-on delay time | $t_{D(on)}$ | $T_J=150^\circ\text{C}$, $V_{CC}=600\text{V}$, $I_C=15\text{A}$, $V_{GE}=-8/15\text{V}$, $R_g=6.2\Omega$, $L=200\mu\text{H}$ | - | 29.6 | - | ns |
| Turn-on rise time | t_r | | - | 58 | - | ns |
| Turn-off delay time | $t_{D(off)}$ | | - | 99.5 | - | ns |
| Turn-off fall time | t_f | | - | 130.5 | - | ns |
| Turn-on energy | E_{on} | | - | 1.006 | - | mJ |
| Turn-off energy | E_{off} | | - | 0.571 | - | mJ |
| Total switching energy | E_{ts} | | - | 1.577 | - | mJ |

Diode switching characteristics (inductive load)

| | | | | | | |
|--------------------------|-----------|---|---|------|---|----|
| Reverse recovery time | t_{rr} | $I_F=15\text{A}$, $V_R=600\text{V}$, $di/dt = -200\text{ A}/\mu\text{s}$ $T_J=25^\circ\text{C}$ | - | 68 | - | ns |
| Reverse recovery charge | Q_{rr} | | - | 787 | - | nC |
| Reverse recovery current | I_{rrm} | | - | 20.6 | - | A |

Fig.1 Gate-Charge characteristics

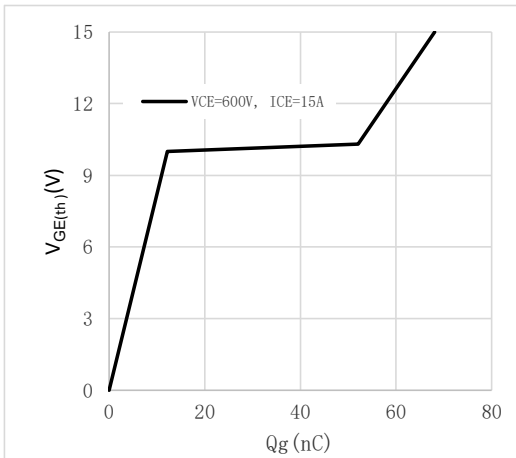


Fig.2 Capacitance characteristics

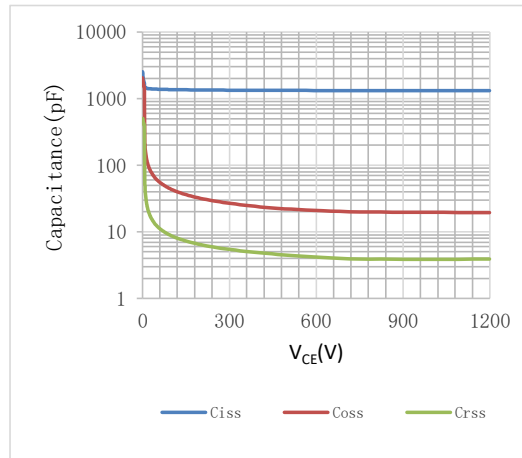


Fig.3 Power dissipation

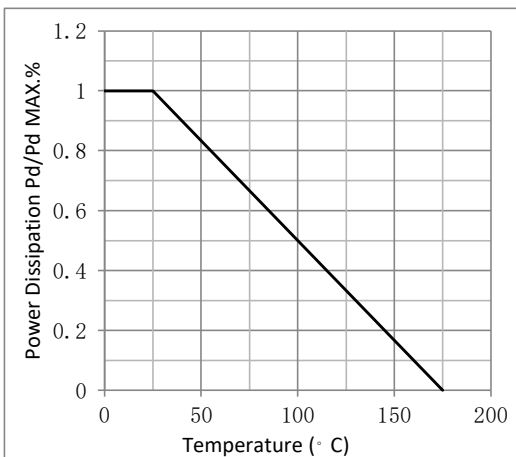


Fig.4 Typical output characteristics

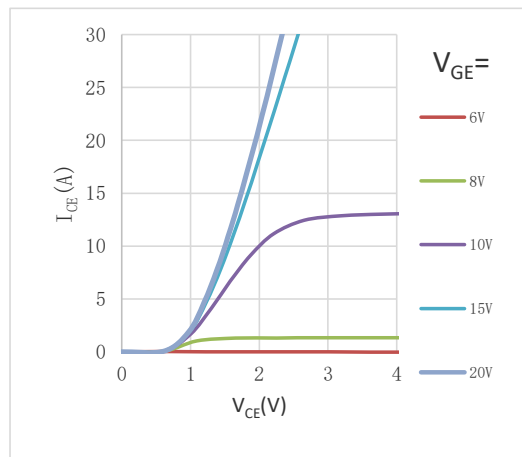


Fig.5 Threshold voltage V.S junction temperature

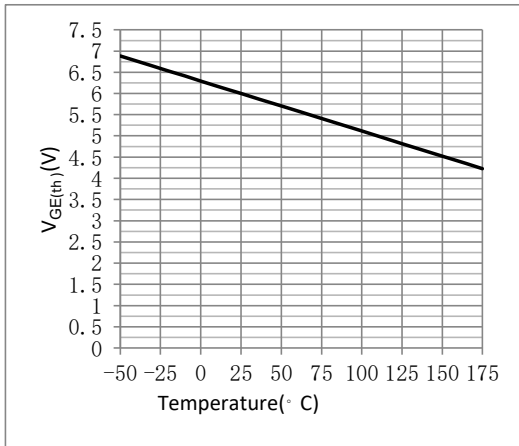


Fig.6 I_C vs. Junction Temperature^③

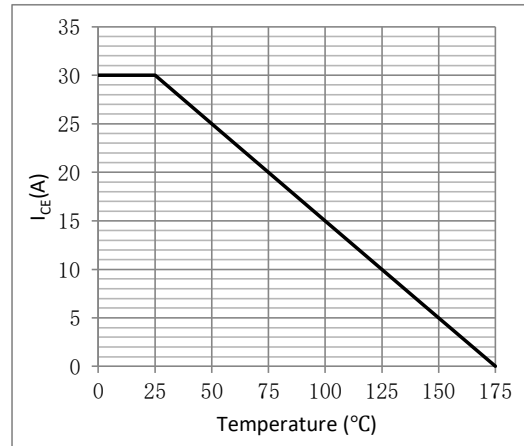


Fig.7 Collector-Emitter VS gate source voltage

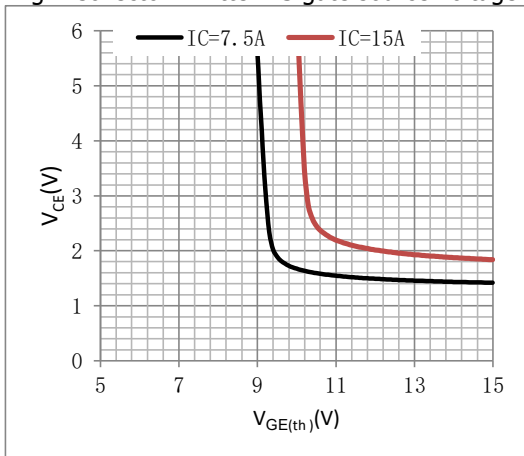


Figure 8. Transfer characteristics

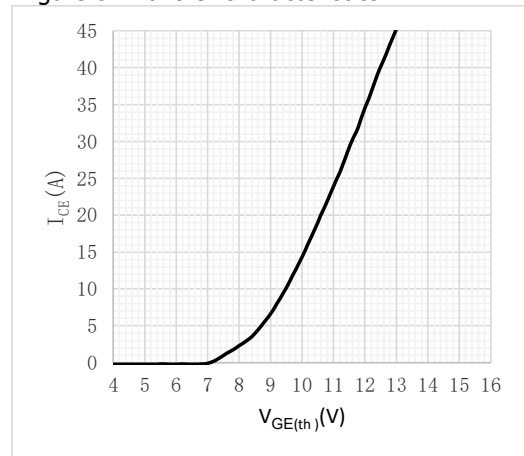


Fig.9 Safe operating area

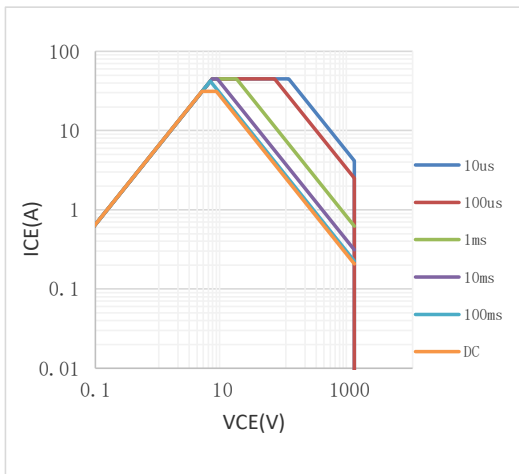


Fig.10 Max transient thermal impedance for IGBT

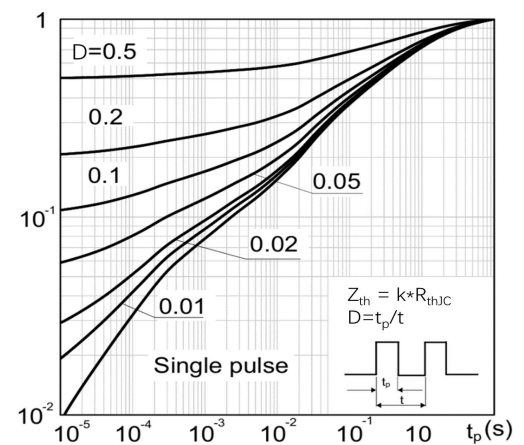


Fig.11 Max transient thermal impedance for Diode

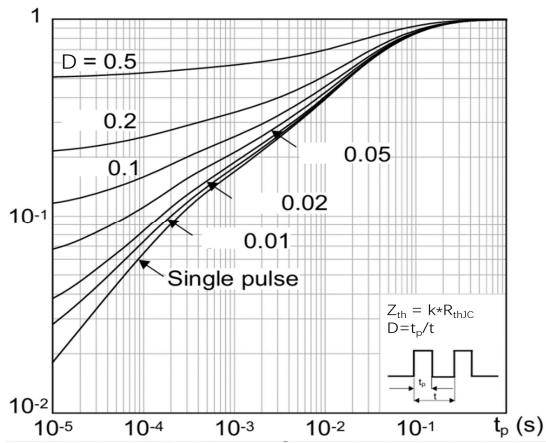
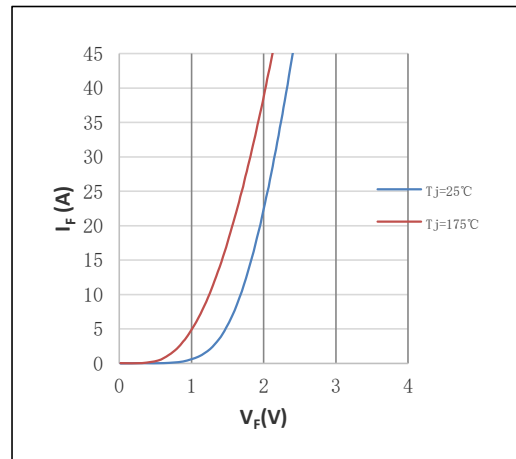
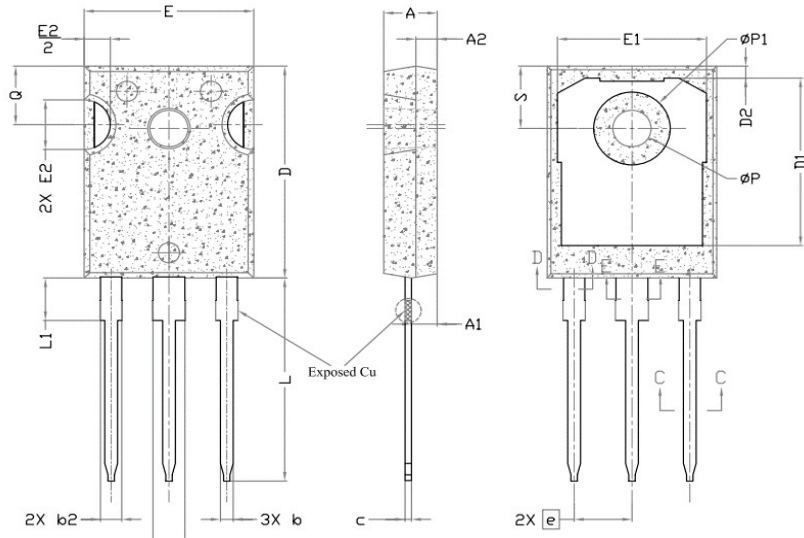


Fig.12 Typical diode forward current as a function of forward voltage



•TO-247 Package Outline



| SYMBOL | DIMENSIONS | | | NOTES |
|--------|------------|-------|-------|-------|
| | MIN. | NOM. | MAX. | |
| A | 4.83 | 5.02 | 5.21 | |
| A1 | 2.29 | 2.41 | 2.55 | |
| A2 | 1.50 | 2.00 | 2.49 | |
| b | 1.12 | 1.20 | 1.33 | |
| b1 | 1.12 | 1.20 | 1.28 | |
| b2 | 1.91 | 2.00 | 2.39 | 6 |
| b3 | 1.91 | 2.00 | 2.34 | |
| b4 | 2.87 | 3.00 | 3.22 | 6, 8 |
| b5 | 2.87 | 3.00 | 3.18 | |
| c | 0.55 | 0.60 | 0.69 | 6 |
| c1 | 0.55 | 0.60 | 0.65 | |
| D | 20.80 | 20.95 | 21.10 | 4 |
| D1 | 16.25 | 16.55 | 17.65 | 5 |
| D2 | 0.51 | 1.19 | 1.35 | |
| E | 15.75 | 15.94 | 16.13 | 4 |
| E1 | 13.46 | 14.02 | 14.16 | 5 |
| E2 | 4.32 | 4.91 | 5.49 | 3 |
| e | 5.44BSC | | | |
| L | 19.81 | 20.07 | 20.32 | |
| L1 | 4.10 | 4.19 | 4.40 | 6 |
| ØP | 3.56 | 3.61 | 3.65 | 7 |
| ØP1 | 7.19REF. | | | |
| Q | 5.39 | 5.79 | 6.20 | |
| S | 6.04 | 6.17 | 6.30 | |

Note:

Ⓞ Practically the current will be limited by PCB, thermal design and operating temperature.
VGE=15V.

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Revision History

| Version | Date | Change |
|---------|-----------|--------|
| A | 2025/4/15 | New |
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